



JOC306XM4 Series

DC Input, Zero-Cross Photo TRIAC Optocoupler

Description

The JOC306XM4 series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon zero-cross photo triac in a plastic SOP4 package. With the robust coplanar double mold structure, JOC306XM4 series provide the most stable isolation feature.

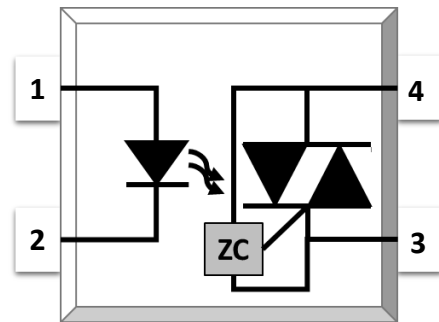
Features

- High isolation 3750 VRMS
- DC input with zero-cross photo triac output
- Operating temperature range - 40 °C to 100 °C
- REACH compliance
- Halogen free
- MSL class 1
- Regulatory Approvals
 - UL
 - VDE
 - CQC

Applications

- Solenoid/valve controls
- Lighting controls
- Motor controls
- Temperature controls
- Static AC power switches
- Solid state relays
- Interfacing microprocessors to 115 to 240VAC peripherals

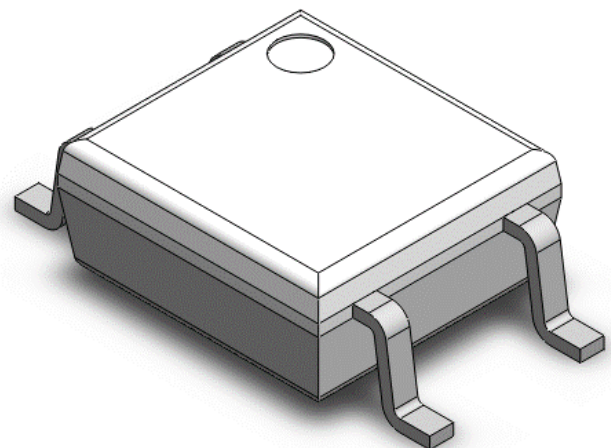
SCHEMATIC



PIN DEFINITION

1. Anode
2. Cathode
3. Terminal
4. Terminal

PACKAGE OUTLINE



ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT	NOTE
INPUT				
Forward Current	I_F	60	mA	
Reverse Voltage	V_R	6	V	
Junction Temperature	T_j	125	°C	
Input Power Dissipation	P_i	100	mW	
OUTPUT				
Off-state Output Terminal Voltage	JOC303XM4	250	V	
	JOC304XM4	400		
	JOC306XM4	600		
	JOC308XM4	800		
Peak Repetitive Surge Current PW=100μs, 120pps	I_{TSM}	1	A	
On-State RMS Current	$I_{T(RMS)}$	100	mA	
Junction Temperature	T_j	125	°C	
Output Power Dissipation	P_o	300	mW	
COMMON				
Total Power Dissipation	P_{tot}	400	mW	
Isolation Voltage	V_{iso}	3750	V _{rms}	1
Operating Temperature	T_{opr}	-40~100	°C	
Storage Temperature	T_{stg}	-55~150	°C	
Soldering Temperature	T_{sol}	260	°C	2

Note 1. AC For 1 Minute, R.H. = 40 ~ 60%

Note 2. For 10 seconds

ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION	NOTE
INPUT							
Forward Voltage	V_F	-	1.24	1.4	V	$I_F=10\text{mA}$	
Reverse Current	I_R	-	-	10	μA	$V_R=6\text{V}$	
Input Capacitance	C_{in}	-	8.5	250	pF	$V=0, f=1\text{kHz}$	
OUTPUT							
Peak Off-state Current, Either Direction	I_{DRM}	-	-	100	nA	$V_{DRM}=\text{Rated } V_{DRM}$ $I_F=0$	3
Peak On-state Current, Either Direction	V_{TM}	-	1.42	2.5	V	$I_{TM}=100\text{mA}$	
Critical Rate of Rise of Off-state Voltage	dV/dt	1000	-	-	$\text{V}/\mu\text{s}$	$V_{PEAK}=\text{Rated } V_{DRM}$	4
TRANSFER CHARACTERISTICS							
LED Trigger Current	JOC3061	I_{FT}	-	-	15	mA	Terminal Voltage = 3V $I_{TM}=100\text{mA}$
	JOC3062		-	-	10		
	JOC3063		-	-	5		
Holding Current	I_H	-	450	-	μA		
Isolation Resistance	R_{iso}	10^{12}	10^{14}	-	Ω	DC500V, 40 ~ 60% R.H.	
Floating Capacitance	C_{IO}	-	0.4	1	pF	$V=0, f=1\text{MHz}$	
ZERO-CROSSING CHARACTERISTICS							
Inhibit Voltage	V_{INH}	-	-	20	V	$I_F=\text{Rated } I_{FT}$	
Leakage in Inhibited State	I_{DRM2}	-	-	500	μA	$I_F=\text{Rated } I_{FT}$ $V_{DRM}=\text{Rated } V_{DRM}$	

Note3. Test voltage must be applied within dV/dt rating.

Note4. Refer to Fig.17 & Fig.18

CHARACTERISTIC CURVES

Fig.1 Forward Current vs. Ambient Temperature

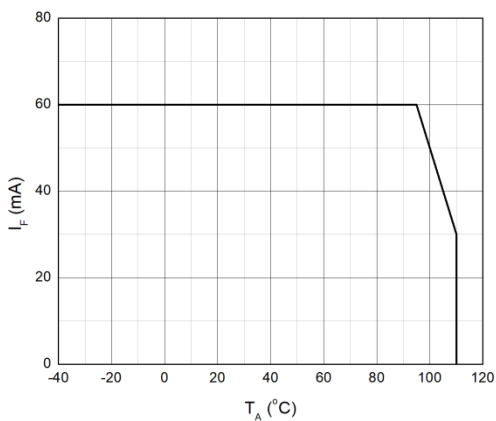


Fig.2 On-state Terminal Current vs. Ambient Temperature

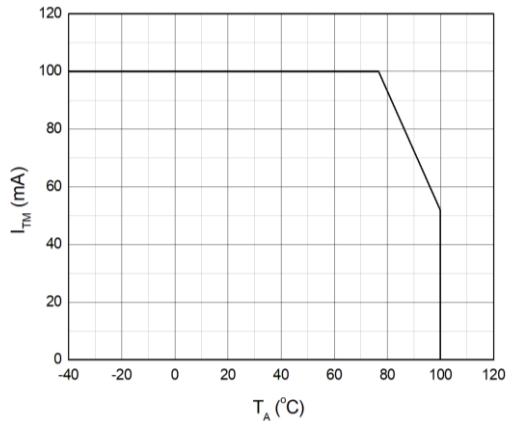


Fig.3 Forward Current vs. Forward Voltage

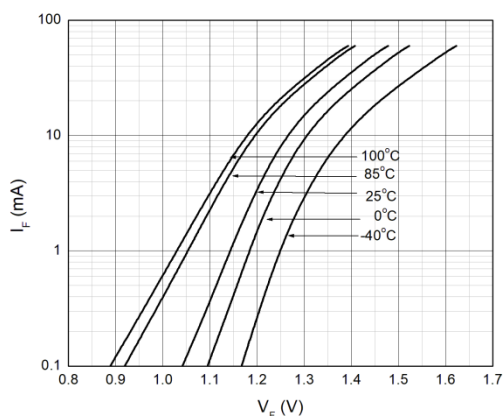


Fig.4 Off-state Terminal Current vs. Ambient Temperature

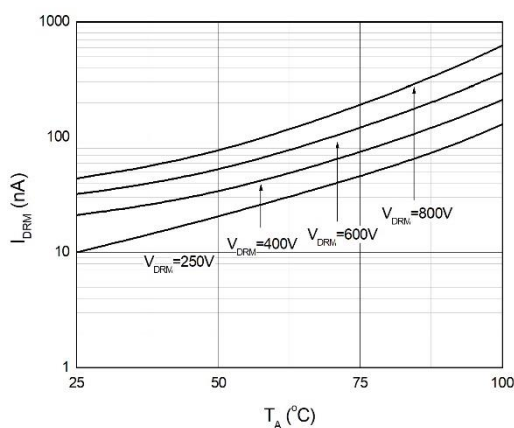


Fig.5 Normalized Off-state Terminal Voltage vs. Ambient Temperature

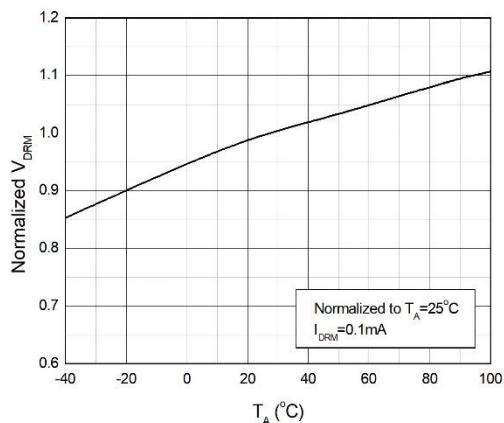
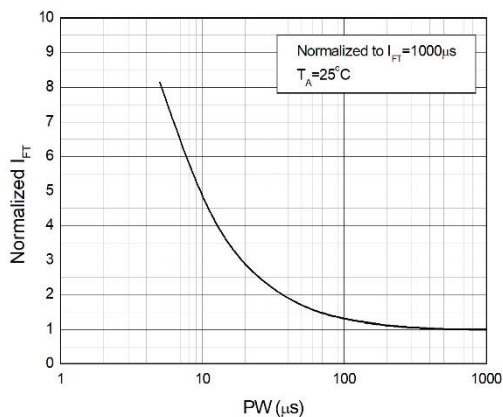


Fig.6 Normalized Trigger Current vs. LED Trigger Pulse Width



CHARACTERISTIC CURVES

Fig.7 Normalized Trigger Current vs. Ambient Temperature

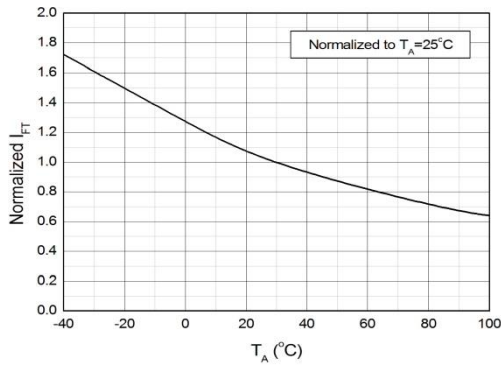


Fig.8 On-state Terminal Voltage vs. Ambient Temperature

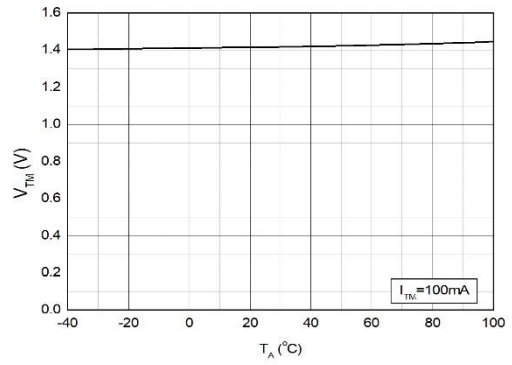


Fig.9 On-state Terminal Voltage vs. On-state Terminal Current

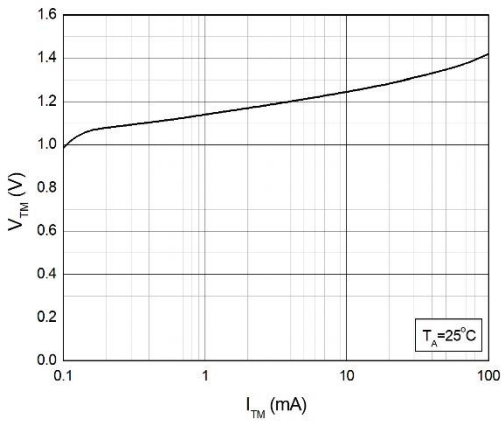


Fig.10 Holding Current vs. Ambient Temperature

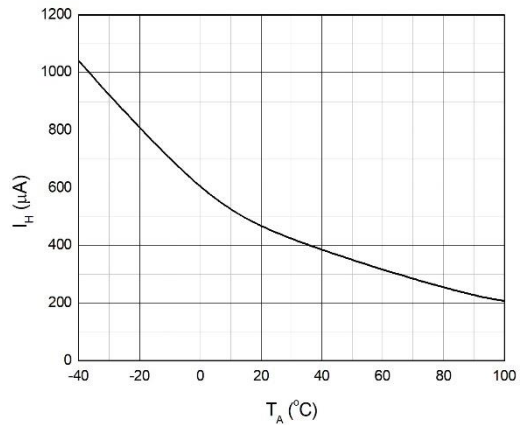


Fig.11 Normalized Inhibit Voltage vs. Ambient Temperature

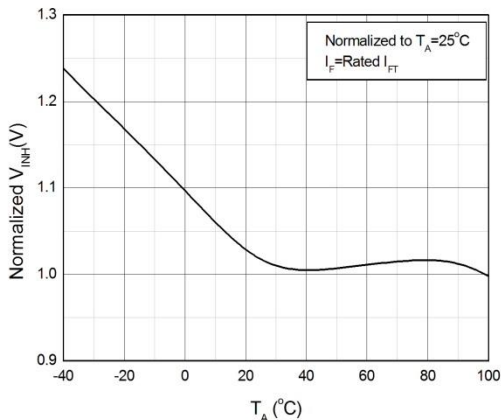
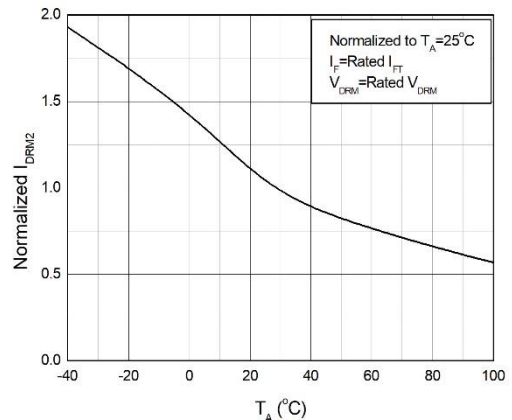


Fig.12 Normalized Leakage in Inhibit State vs. Ambient Temperature



CHARACTERISTIC CURVES

Fig.13 Turn On Time vs. Forward Current

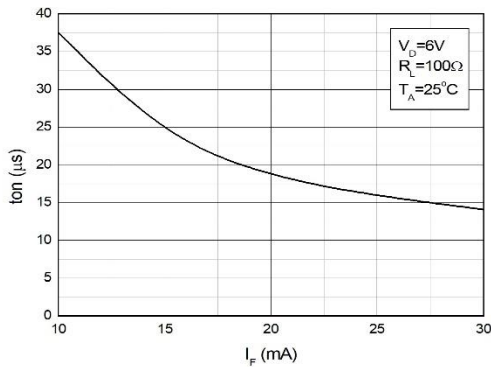
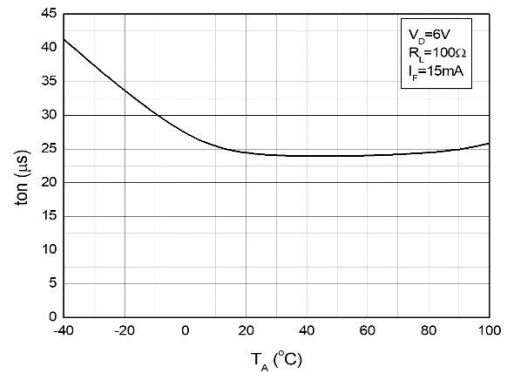


Fig.14 Turn On Time vs. Ambient Temperature



TEST CIRCUITS

Fig.15 Test Circuits of Turn On Time

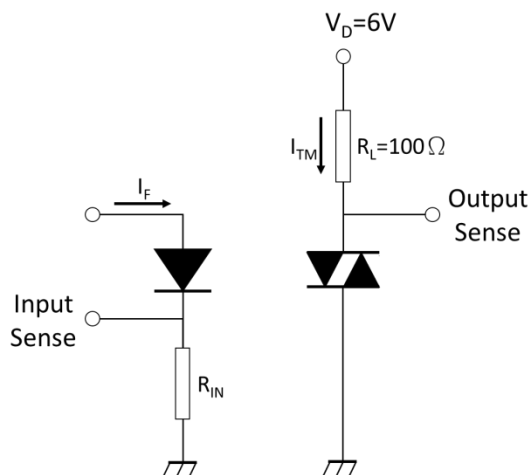


Fig.16 Waveforms of Turn On Time

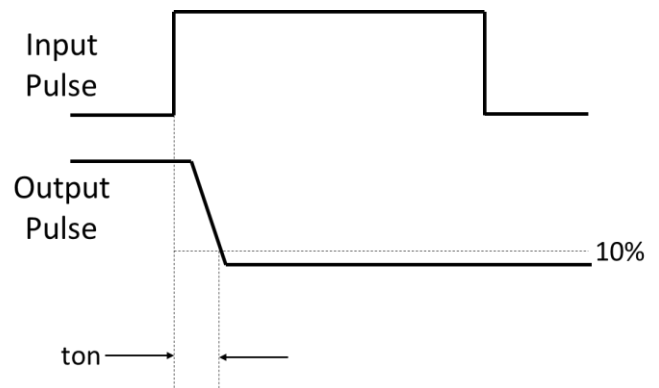


Fig.17 Test Circuits of dV/dt

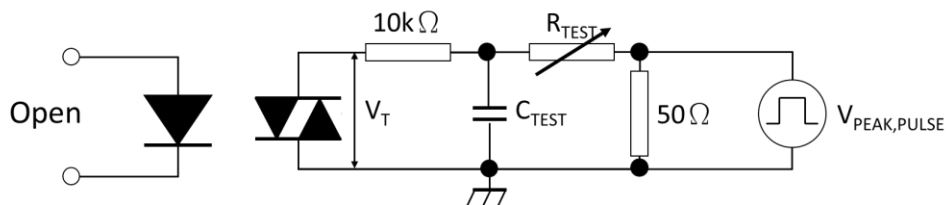
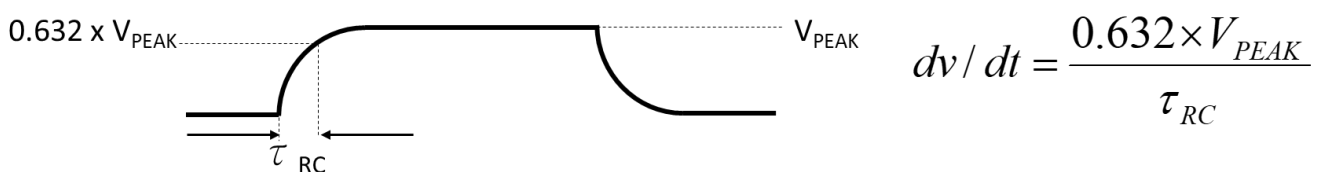
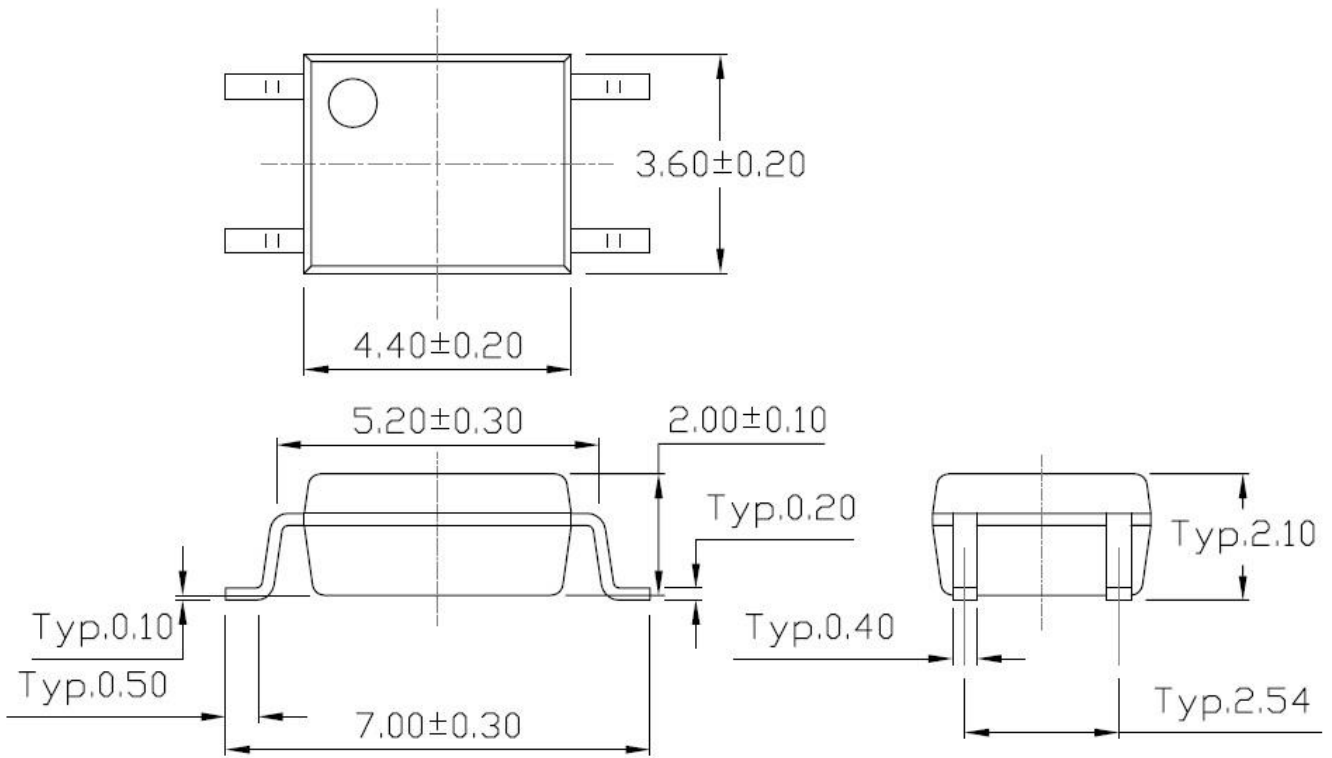


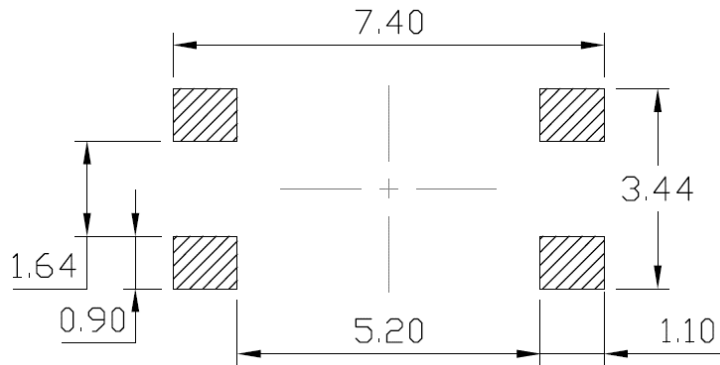
Fig.18 Waveforms of dV/dt



PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

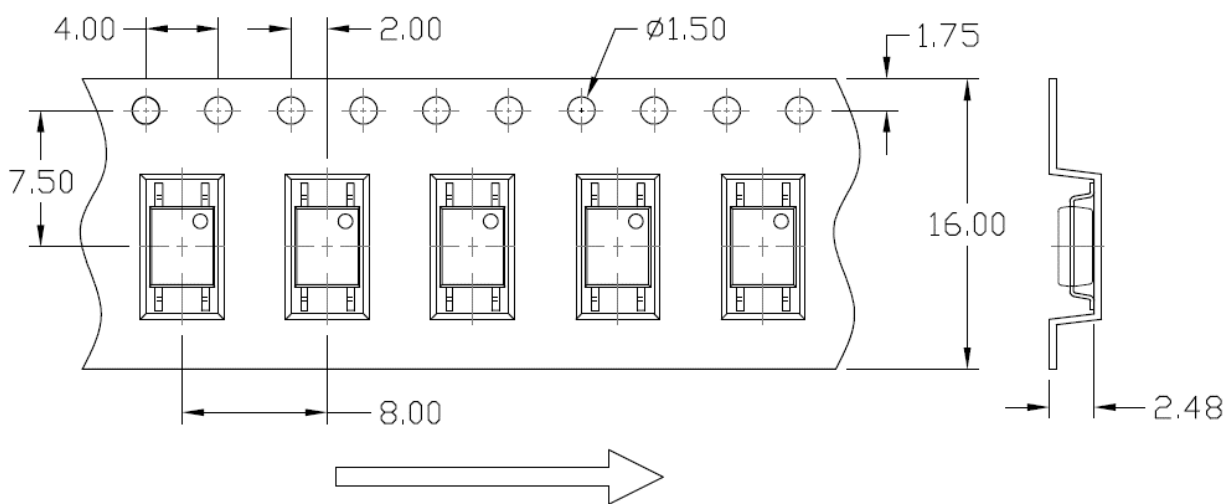


Recommended Solder Mask (Dimensions in mm unless otherwise stated)

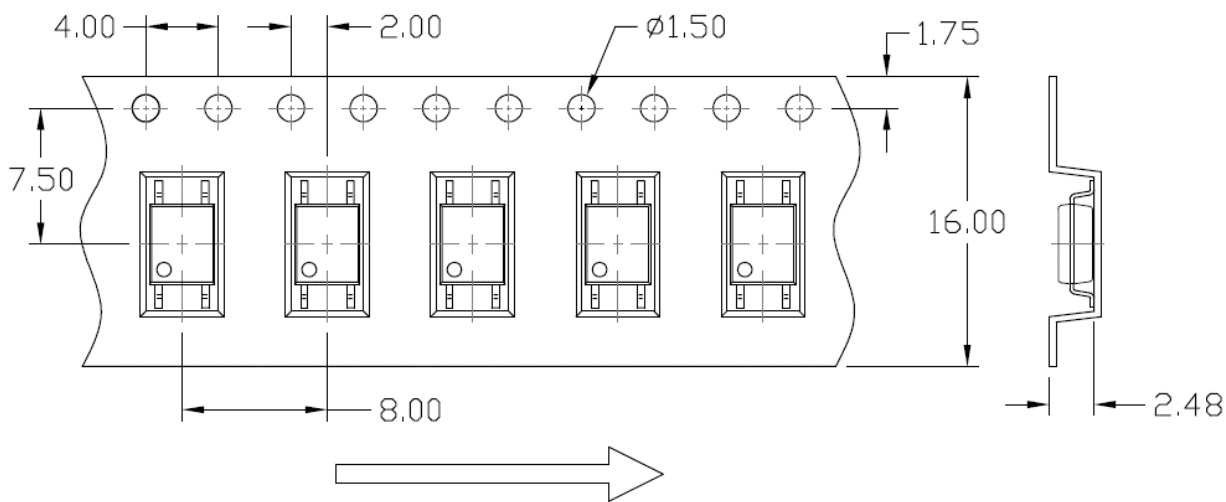


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option T1

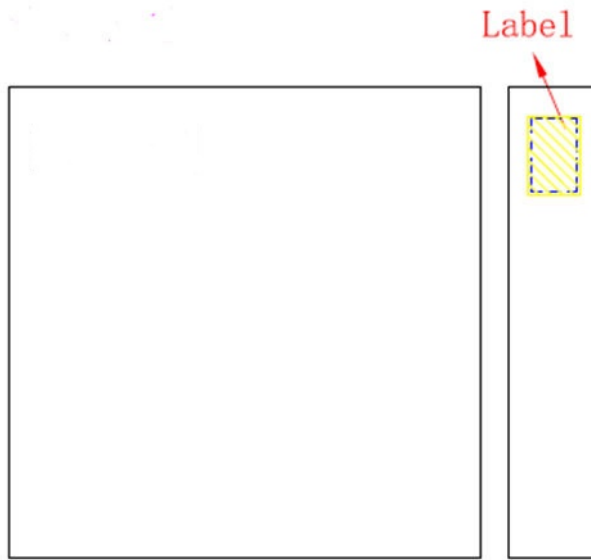


Option T2



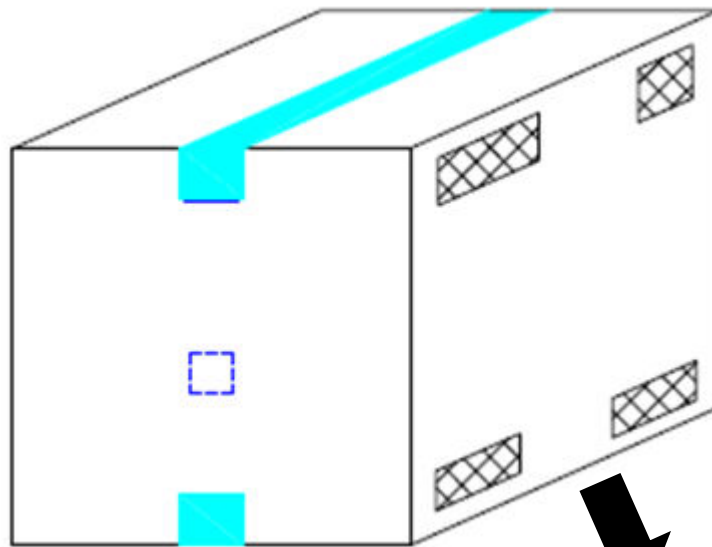
BOX SPECIFICATIONS (Reel Type)

Inner Box

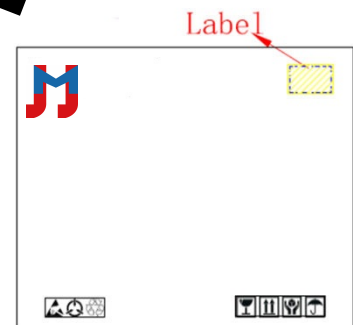


- L x W x H = 36cm x 36cm x 6.9cm

Outer Box

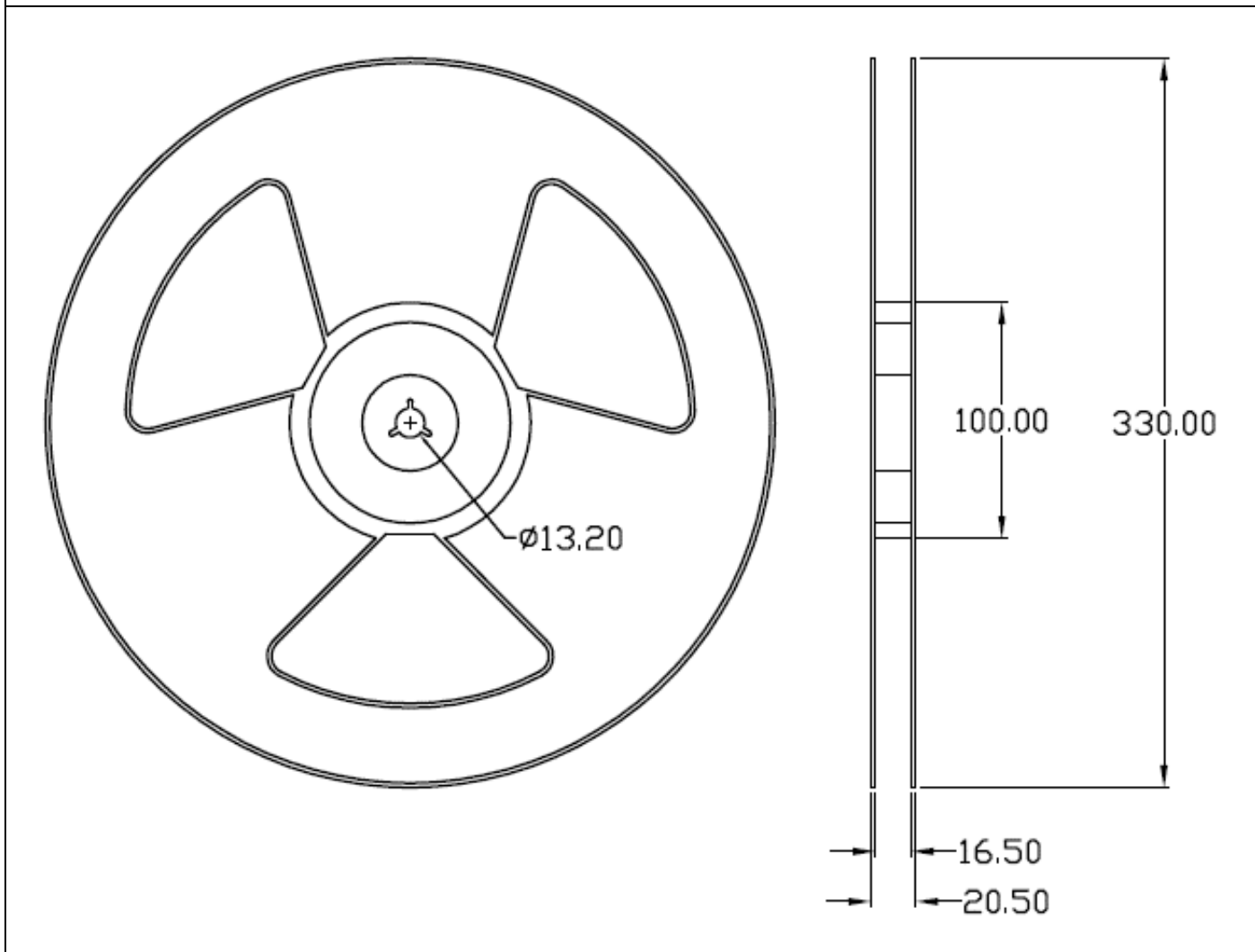


- L x W x H = 45cm x 38cm x 38cm



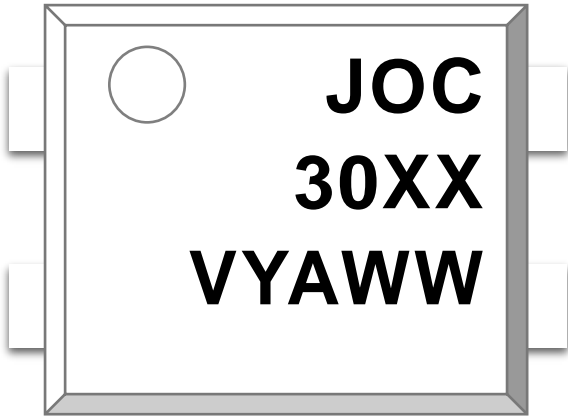
REEL SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option T1 & T2



ORDERING AND MARKING INFORMATION

MARKING INFORMATION



JOC : Company Abbr.
30XX : Part Number & Rank
V : VDE Option
Y : Fiscal Year
A : Manufacturing Code
WW : Work Week

ORDERING INFORMATION

JOC30XXMX(Z)-GV

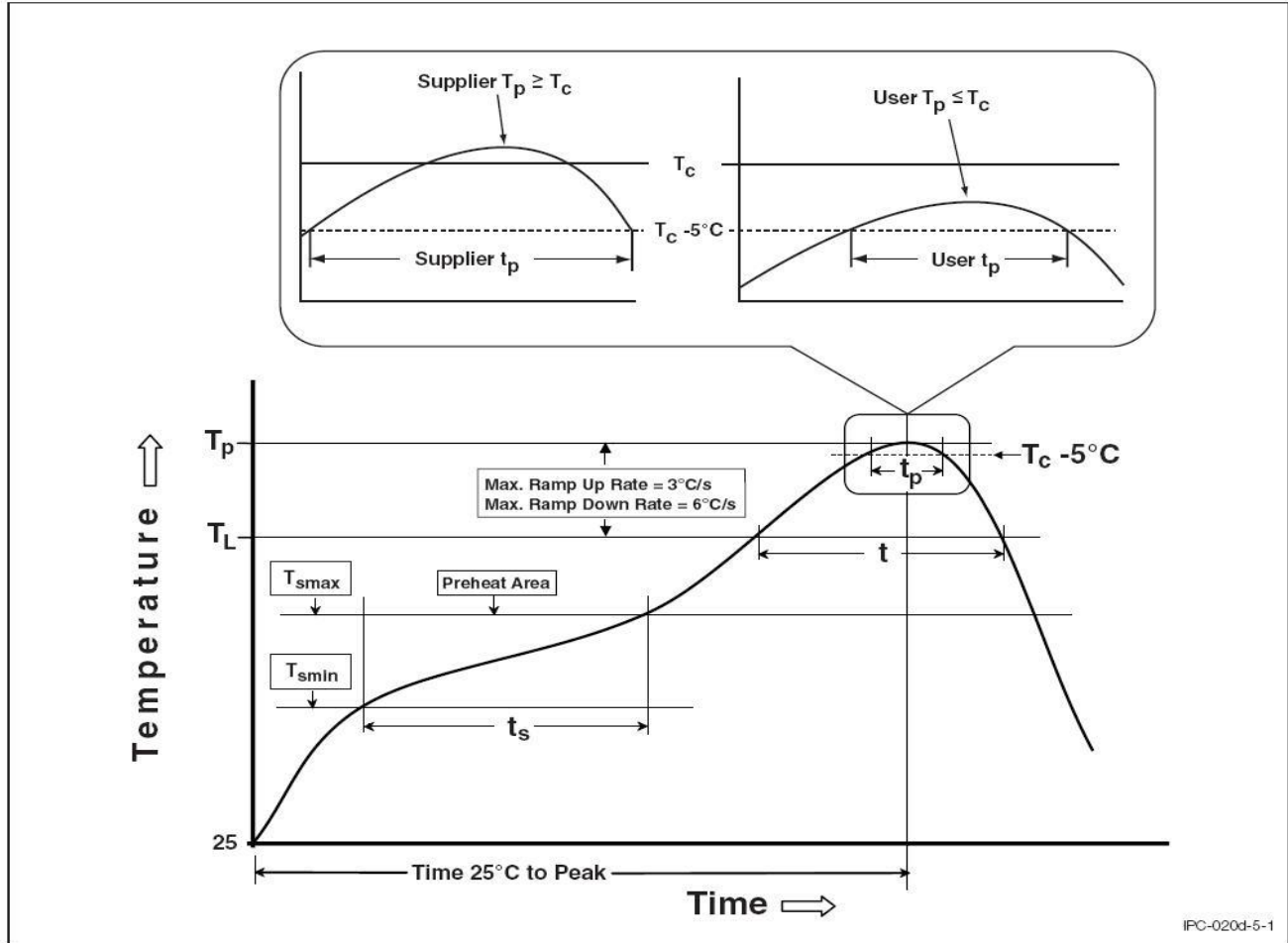
JOC – Company Abbr.
 MX – SOP Package
 30XX – Rank (31/32/33/41/42/43/61/62/63/81/82/83)
 Z – Tape and Reel Option (T1/T2)
 G – Green
 V – VDE Option (V or None)

Packing Quantity

Option	Quantity – Inner box	Quantity – Outer box	Quantity
T1	3 Reels/Inner box	5 Inner box/Outer box = 45k Units	3000Units/Reel
T2	3 Reels/Inner box	5 Inner box/Outer box = 45k Units	3000Units/Reel

REFLOW INFORMATION

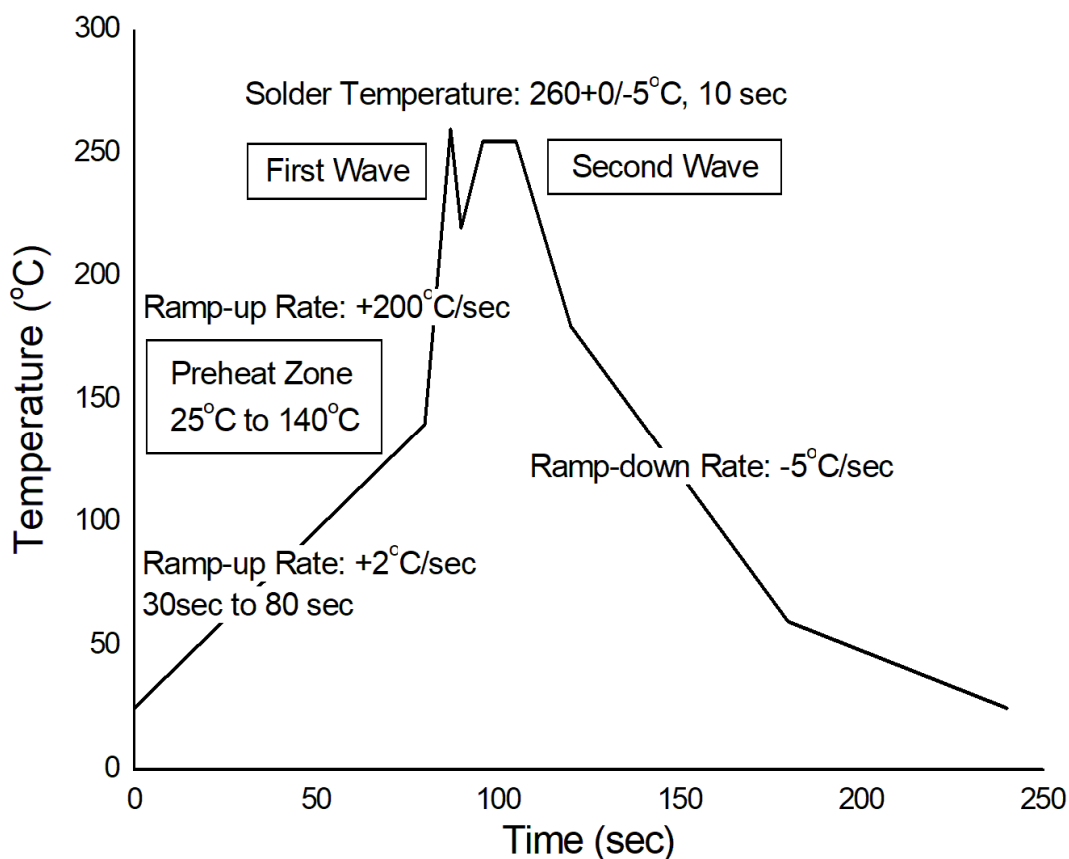
REFLOW PROFILE



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmmin)	100	150°C
Temperature Max. (Tsmmax)	150	200°C
Time (ts) from (Tsmmin to Tsmmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3°C/second max.	3°C/second max.
Liquidous Temperature (TL)	183°C	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (tP) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

TEMPERATURE PROFILE OF SOLDERING

WAVE SOLDERING (JESD22-A111 COMPLIANT)



HAND SOLDERING BY SOLDERING IRON

Soldering Temperature	380+0/-5°C
Soldering Time	3 sec max.

- One time soldering is recommended for all soldering method.
- Do not solder more than three times for IR reflow soldering.

DISCLAIMER

- JIEJIE is continually improving the quality, reliability, function and design. JIEJIE reserves the right to make changes without further notices.
- The characteristic curves shown in this datasheet are representing typical performance which are not guaranteed.
- JIEJIE makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, JIEJIE disclaims (a) any and all liability arising out of the application or use of any product, (b) any and all liability, including without limitation special, consequential or incidental damages, and (c) any and all implied warranties, including warranties of fitness for particular
- The products shown in this publication are designed for the general use in electronic applications such as office automation, equipment, communications devices, audio/visual equipment, electrical application and instrumentation purpose, non-infringement and merchantability.
- This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or lifesaving applications or any other application which can result in human injury or death.
- Please contact JIEJIE sales agent for special application request.
- Immerge unit's body in solder paste is not recommended.
- Parameters provided in datasheet may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated in each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify JIEJIE's terms and conditions of purchase, including but not limited to the warranty expressed therein.
- Discoloration might be occurred on the package surface after soldering, reflow or long-time use. It neither impacts the performance nor reliability.